



GS600M Online Visual Dispensing Machine MEMS Microphone MEMS accelerometer MEMS Barometer

Our Product Introduction

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Basic Information

- Place of Origin: China
- Brand Name: MingSeal
- Certification: ISO
- Model Number: GS600M
- Minimum Order Quantity: 1
- Price: \$28000-\$150000
- Packaging Details: WOODEN
- Delivery Time: 5-60 days
- Payment Terms: L/C, T/T, D/A, D/P, MoneyGram, Western Union



Product Specification

- Condition: New
- Automatic Grade: Automatic
- Warranty: 1 Year
- Product Name: GS600M Online Visual Dispensing Machine
- Application Fields: Die Form Packaging Of Lead Frame, Substrate, Shell
- Applicable Process: Chip Encapsulation Solder Paste Gluing Potting component Reinforcement
- Footprint W×D×H: 2050×1535×2085mm
- Weight: 1.5t
- Power Supply: 200~240VAC, 47~63HZ (Single-phase Voltage Adaptation Power Supply)
- Electric Current: 35A
- Power: 7KW
- Inhale: 5.0-7.0 Kg/cm2
- Highlight: Solder Paste circuit board pick and place



More Images



GS600M Online Visual Dispensing Machine

GS600M is a fully- automatic online dispensing platform developed based on the needs of the MEMS industry. It can provide one- stop solutions for on- line ASIC chip encapsulation, precision solder paste dispensing and multiple fool- proof detection, etc. in the MEMS process. High- quality control of the entire production process is realized. The on-line workstation operation can also be selected.

Features and Advantages

On-line Mode

Yield Improvement

Work positions are inspected before and after operation, and the final station is professionally inspected to achieve multiple fool proof.

Full Automation

The on- line mode is used to minimize manual intervention.

Prevention of Whole Line Downtime

Operation tracks / conveyor tracks are separated, so that shutdown of a single machine does not affect the operation of the whole line.

Application Fields

MEMS Microphone MEMS accelerometer MEMS Barometer

Technical Specifications

Model GS600M		
Application Fields	Die form packaging of lead frame, substrate, shell	
Applicable Process	Chip Encapsulation,Solder paste gluing ,Potting ,component reinforcement	
Cleanliness Level	Cleanliness of working area Class 100 (Class 1000 workshop) Class 10 (Class 100 workshop)	
Transmission System	Transmission mechanisms X/Y:Linear motor Z:Servo motor&Screw module	
	Repeatability (3sigma)	X/Y: ±0.010mm Z: ±0.015mm
	Positioning accuracy (3sigma)	X/Y: ±0.015mm Z: ±0.025mm
	Max. movement speed	X/Y :1000mm/s Z: 500mm/s
	Max. accelerated velocity	X/Y: 1g Z: 0.5g
	Grating resolution	1 μ m
	Z axis height calibration&compensation Method	Laser sensor (Laser sensor)
	Laser sensor accuracy	±0.01mm
Dispensing Capability	Dispensing method	Piezo-pump (Mingseal self-developed)
	Glue control accuracy	±3%/1mg (as per actual adhesive specific gravity)
	Min. single dot glue weight	0.001mg/dot (as per actual adhesive specific gravity)
	Max. fluid viscosity	200000cps
	Max. jetting frequency	1000Hz
	Runner/nozzle heating temperature	Room temperature~200°C
Runner/nozzle heating temp. deviation	±2°C	
Facilities	Footprint W× D × H	2050× 1535×2085mm
	Weight	1.5t
	Power supply	200~240VAC,47~63HZ (Single-phase voltage adaptation power supply)
	Electric current	35A
	Power	7KW
Inhale	5.0-7.0 kg/cm2	



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